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**PATENT ABSTRACTS OF JAPAN**(21) Application number: **10084230**(51) Intl. Cl.: **B24B 37/00 H01L 21/304**(22) Application date: **30.03.98**

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**(54) POLISHING PAD,  
POLISHING DEVICE, AND  
POLISHING METHOD**

(57) Abstract:

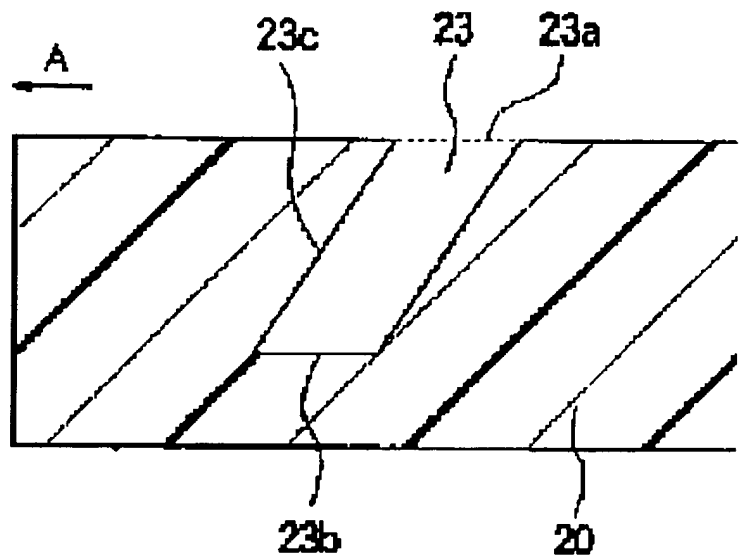
**PROBLEM TO BE SOLVED:** To provide a polishing pad for chemical-mechanical polishing, capable of surely holding polishing slurry, and increasing the chance to make the polishing slurry contact with a wafer to improve the quality of polishing, and a polishing device, a polishing method using the polishing pad.

**SOLUTION:** With a disc-like polishing pad for use in polishing process by chemical-mechanical polishing method, a recessed part 23 is formed in the polishing pad. At least a part of the bottom part 23b of the recessed part 23 is positioned on the outer peripheral side relative to an opening part 23a of the recessed part 23 or on the reverse side (A side) to the direction of rotation of the polishing pad, and at least a side wall 23c on the outer peripheral side of the

*recessed part*

recessed part 23 or on the reverse side to the direction of rotation of the polishing pad, is formed to be reversely tapered in relation to the surface of the polishing pad.

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